L Number	Hits	Search Text	DB	Time stamp
1	27408	tape with carrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 09:34
2	68781	tcp (tape with carrier with (package packaged packaging)) (tape with carrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 09:36
3	2598502	semiconductor die dice chip ic (integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 09:37
4	1426855	leadframe lead (lead adj frame)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 09:37
5	9959	(tcp (tape with carrier with (package packaged packaging)) (tape with carrier)) and (semiconductor die dice chip ic (integrated adj circuit)) and (leadframe lead (lead adj frame))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 09:38
6	3301	(tcp (tape with carrier with (package packaged packaging)) (tape with carrier)) same (semiconductor die dice chip ic (integrated adj circuit)) same (leadframe lead (lead adj frame))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 09:39
7	415339	(leadframe lead (lead adj frame)) and (trace land pad electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 09:39
8	609711	(leadframe lead (lead adj frame)) and (trace land pad terminal electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 09:39
9	2291	((tcp (tape with carrier with (package packaged packaging)) (tape with carrier)) same (semiconductor die dice chip ic (integrated adj circuit)) same (leadframe lead (lead adj frame))) and (trace land pad terminal electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 09:40
10	6781	((tcp (tape with carrier with (package packaged packaging)) (tape with carrier)) and (semiconductor die dice chip ic (integrated adj circuit)) and (leadframe lead (lead adj frame))) and (trace land pad terminal electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 09:40
11	1184	(((tcp (tape with carrier with (package packaged packaging)) (tape with carrier)) same (semiconductor die dice chip ic (integrated adj circuit)) same (leadframe lead (lead adj frame))) and (trace land pad terminal electrode)) and (bga ball bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 09:40